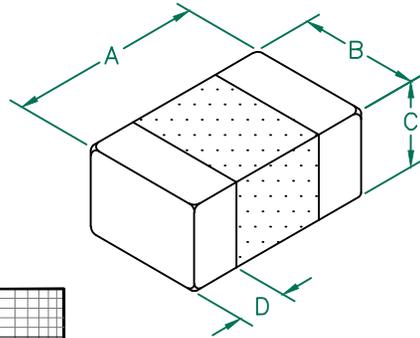


# HI0805R800R-10

## PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.20 [.008]
D	0.51 [.020]	+ 0.25 [.010]



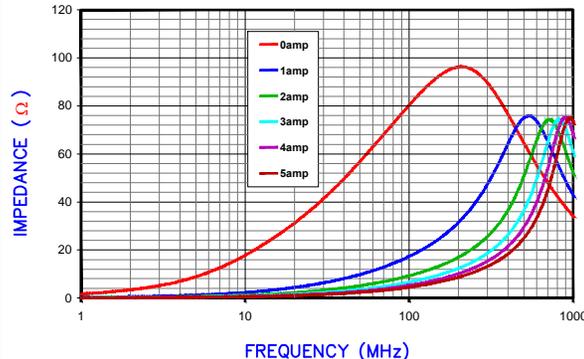
## ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz ( $\Omega$ )	DCR ( $\Omega$ )	Rated Current
Nominal	80		
Minimum	60		
Maximum	100	0.010	5000 mA

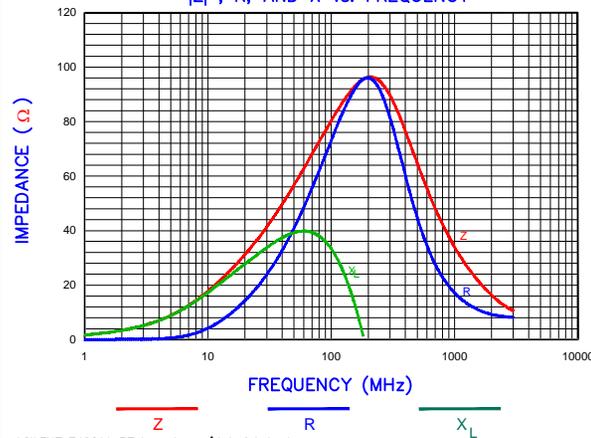
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REE, PAPER TAPE.
2. TERMINATION FINISH IS 100% TIN.
3. CONTINUOUS CURRENT RATING OF 5000 mA.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATING TEMPERATURE TEMP:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  (INCLUDING SELF-HEATING)

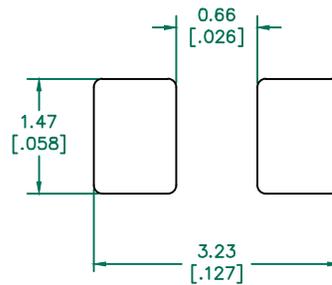
Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)  
|Z|, R, AND X vs. FREQUENCY

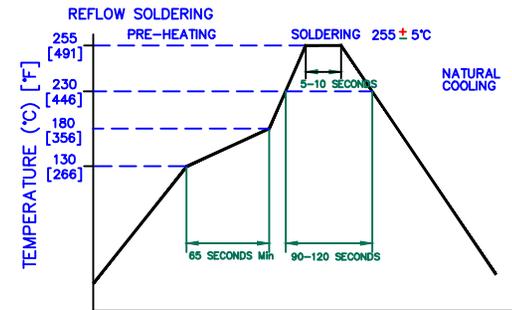


## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [.030] to this dimension.)

## RECOMMENDED SOLDERING CONDITIONS



RoHS

DIMENSIONS ARE IN mm [INCHES].			This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.		
E	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER:	REV PART TYPE: DRAWN BY:
D	CHANGE TO PAPER TAPE	03/03/10	JUN	HI0805R800R-10	E CO-FIRE TMB
C	UPDATE COMPANY LOGO	06/15/09	JRK	DATE: 04/02/04	SCALE: NTS
B	UPDATE COMPANY LOGO	01/17/08	JRK	DATE: 04/02/04	SHEET: 1 of 1
A	ORIGINAL DRAFT	04/02/04	TMB	CAD # HI0805R800R-10-E	TOOL # -
REV	DESCRIPTION	DATE	INT		